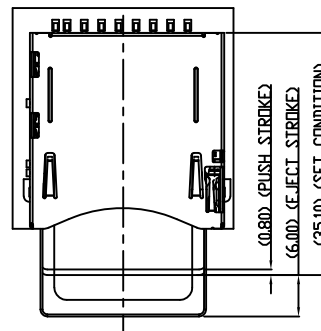


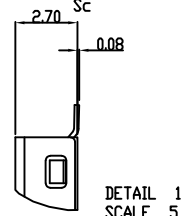
更改 REV	修改内容 MODIFICATION
A	ECN02841
B	ECN03882
C	ECN04890

NOTES:
 1. MATERIAL:
 INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,
 UL94V-0, BLACK
 CONTACT: PHOSPHOR BRONZE
 2. PLATING:
 CONTACT AREA: 10 μ GOLD OVER 50 μ NICKEL
 SOLDER TAIL: G/F OVER 50 μ NICKEL

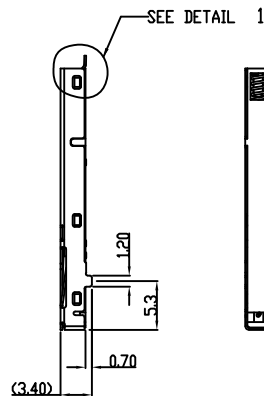
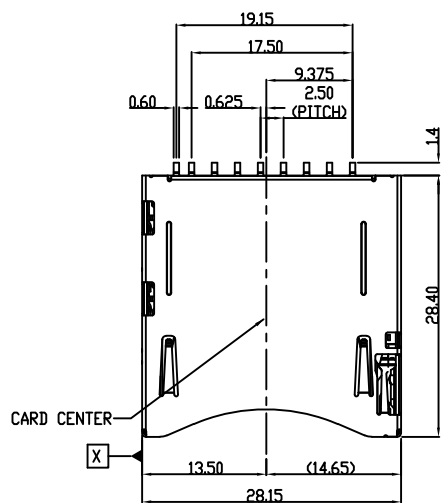
Card detection switch		Write protection switch		
When card is ejected	When card is inserted	When card is ejected	When card is inserted	
OPEN	CLOSE	OPEN	Write protect	Write enable
Cd Sc	Cd Sc	Wp Sc	Wp Sc	Wp Sc



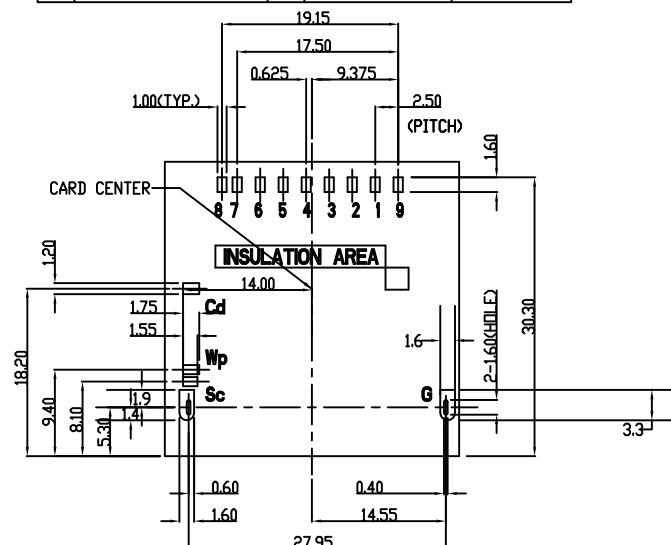
ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BODY	1	LCP	
2	SLIDER	1	LCP	
3	CONTACT	9	PHOSPHOR BRONZE	GOLD PLATE
4	WRITE PROTECTION PIN	1	PHOSPHOR BRONZE	GOLD FLASH
5	CARD DETECTION PIN	1	PHOSPHOR BRONZE	GOLD FLASH
6	COMMON PIN	1	PHOSPHOR BRONZE	GOLD FLASH
7	SHELL	1	STAINLESS	GOLD FLASH
8	DRAG LINK	1	STAINLESS	
9	SPRING	1	PIANO WIRE	NICKEL PLATE



DETAIL 1
SCALE 5



PIN NO.	PIN ASSIGNMENT	PIN NO.	PIN ASSIGNMENT
1	DAT3/CS/CD	8	DAT1
2	CMD	9	DAT2
3	VSS1	Wp	WRITE PROTECTION
4	VDD	Cd	CARD DETECTION
5	CLK	Sc	COMMON PIN
6	VSS2	G	SDIO / GROUND
7	DAT0		



RECOMMEND PC BOARD LAYOUT
GENERAL TOLERANCE: ±0.05mm

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司
X ± 0.50	X* ± 5°	
X ± 0.30	X* ± 2°	
.XX ± 0.20	.XX* ± 1°	
名 称(TITLE) SD MEMORY CARD CONNECTOR (PUSH/PUSH TYPE)		
单 位(UNIT) mm	料 号(PART NO.) 7SDCP-B0-1010	图 号(DWG NO.) 7SDCP-B0-1010-C
审 核(APPROVAL)	核 对(CHECKED)	图 数(SHEET) 1 / 1
		版 次(REV) C

